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Flexible -55 to 150°C

Good Adhesive Strength

High Melt-flow >135°C

>1000 V Insulation @ 3 mil

UL 94V-O/UL 746A Rated

**IDEAL FOR:**

- Thermal Grease Replacement
- Thermal Gasket Replacement
- Thermal Adhesive Paste Substitute
- BGA Thermal Interface Die-Attach

**DESCRIPTION:**

CB7135 is an alumina crystallite filled, electrically insulating, medium bond strength thermal interface material. It is designed to enhance thermal transfer from power device to heat-sink. CB7135 is dry and handles well with automated excise-placement equipment and forms good bond with placement pressure similar to paste adhesives.

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**AVAILABILITY:**

CB7135 is available in sheet sizes, reel, and as custom preforms. Standard thicknesses are 0.003" and 0.006". Special thicknesses are available.

**APPLICATION PROCEDURES:**

- ( 1 ) Keep at room temperature for 15 minutes before using.
- ( 2 ) Cut or pre-cut to desired size and shape.
- ( 3 ) Place COOL-BOND between device and heat-sink.
  
- ( 4 ) If it is pre-applied onto heatsink or CPU, place COOL-PAD onto heated heat-sink and heat-spreader.

**CAUTION:** This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details. The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

While AI Technology owns all proprietary rights of material formulations of its products, specific usage in the manufacturing of certain products may involve patent rights of other companies.

**COOL-BOND**  
**CB7135**

**TYPICAL PROPERTIES\***

Electrical Resistivity ( 25 °C/ As is )	>1x10 <sup>14</sup> ohm-cm
Dielectric Strength (Volts/mil)	>550
Glass Transition Temp.(°C)	-55 ±10%
Lap-Shear Strength	<600 psi <4.1 N/mm <sup>2</sup>
Device Push-off Strength	>800 psi >5.5 N/mm <sup>2</sup>
Hardness (Type)	<60 (A)
Cured Density (gm/cc)	1.2 ±10%
Thermal Conductivity	14 Btu-in/hr-ft <sup>2</sup> -°F ±10% 2.0 W/m-°C ±10%
Linear Thermal Expansion Coeff. (ppm/°C)	110 ±15%
Maximum Continuous Operation Temp. (°C)	<150

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**MELT/FLOW CONDITIONS**

Temperature	Time	Pressure
>135°C	0.5 sec	Nominal

**SHELF LIFE:**

Storage temperature	Shelf Life
0°-5°C	1 yr in sealed package